

FDP075N15A_F102 / FDB075N15A

N-Channel PowerTrench® MOSFET

150 V, 130 A, 7.5 mΩ

Features

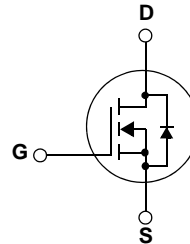
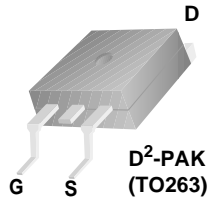
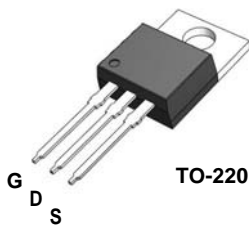
- $R_{DS(on)} = 6.25 \text{ m}\Omega$ (Typ.) @ $V_{GS} = 10 \text{ V}$, $I_D = 100 \text{ A}$
- Fast Switching
- Low Gate Charge
- High Performance Trench Technology for Extremely Low $R_{DS(on)}$
- High Power and Current Handling Capability
- RoHS Compliant

Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- Synchronous Rectification for ATX / Server / Telecom PSU
- Battery Protection Circuit
- Motor Drives and Uninterruptible Power Supplies
- Micro Solar Inverter



MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted*

Symbol	Parameter	FDP075N15A_F102 FDB075N15A	Unit
V_{DSS}	Drain to Source Voltage	150	V
V_{GSS}	Gate to Source Voltage	± 20	V
I_D	Drain Current	-Continuous ($T_C = 25^\circ\text{C}$)	130
		-Continuous ($T_C = 100^\circ\text{C}$)	92
I_{DM}	Drain Current	- Pulsed (Note 1)	522
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	588
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0
P_D	Power Dissipation	($T_C = 25^\circ\text{C}$)	333
		- Derate above 25°C	2.22
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

*Package limitation current is 120A.

Thermal Characteristics

Symbol	Parameter	FDP075N15A_F102 FDB075N15A	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	0.45	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (minimum pad of 2 oz copper), Max	62.5	
	Thermal Resistance, Junction to Ambient D2-PAK (1 in ² pad of 2 oz copper), Max	40	

Package Marking and Ordering Information

Device Marking	Device	Package	Description	Quantity
FDP075N15A	FDP075N15A_F102	TO-220	F102: Trimmed Leads	50

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB075N15A	FDB075N15A	D2-PAK	330mm	24mm	800

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	150	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, Referenced to 25°C	-	0.1	-	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 120\text{V}, V_{GS} = 0\text{V}$ $V_{DS} = 120\text{V}, T_C = 150^\circ\text{C}$	-	-	1 500	μA
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$	-	-	± 100	μA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	2.0	-	4.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}, I_D = 100\text{A}$	-	6.25	7.5	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS} = 10\text{V}, I_D = 100\text{A}$	-	164	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 75\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$	-	5525	7350	pF
C_{oss}	Output Capacitance		-	516	685	pF
C_{riss}	Reverse Transfer Capacitance		-	21	-	pF
$C_{oss(er)}$	Energy Related Output Capacitance	$V_{DS} = 75\text{V}, V_{GS} = 0\text{V}$	-	909	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 75\text{V}, I_D = 100\text{A}$ $V_{GS} = 10\text{V}$	-	77	100	nC
Q_{gs}	Gate to Source Gate Charge		-	26	-	nC
Q_{gs2}	Gate Charge Threshold to Plateau		-	11	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		(Note 4)	-	16	-
ESR	Equivalent Series Resistance(G-S)	$f = 1\text{MHz}$	-	2.29	-	Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 75\text{V}, I_D = 100\text{A}$ $V_{GS} = 10\text{V}, R_{GEN} = 4.7\Omega$	-	28	66	ns
t_r	Turn-On Rise Time		-	37	84	ns
$t_{d(off)}$	Turn-Off Delay Time		-	62	134	ns
t_f	Turn-Off Fall Time		(Note 4)	-	21	52

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	130	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	520	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_{SD} = 100\text{A}$	-	-	1.25	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{V}, V_{DD} = 75\text{V}, I_{SD} = 100\text{A}$	-	97	-	ns
Q_{rr}	Reverse Recovery Charge	$di_F/dt = 100\text{A}/\mu\text{s}$	-	264	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Starting $T_J = 25^\circ\text{C}$, $L = 3\text{ mH}$, $I_{AS} = 19.8\text{ A}$
3. $I_{SD} \leq 100\text{ A}$, $di/dt \leq 200\text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

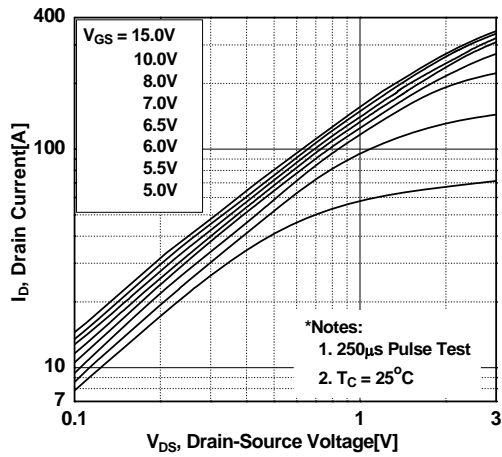


Figure 2. Transfer Characteristics

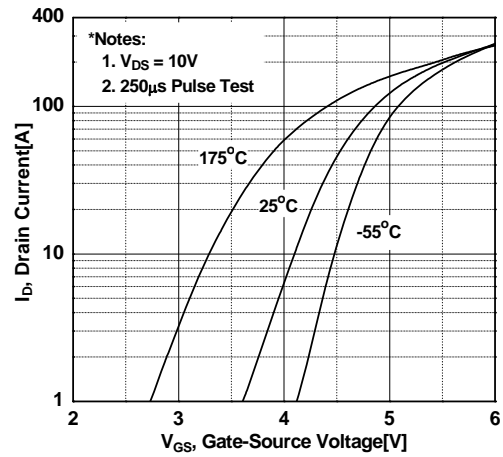


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

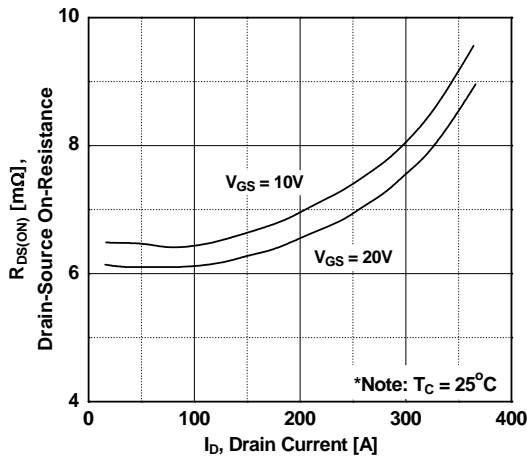


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

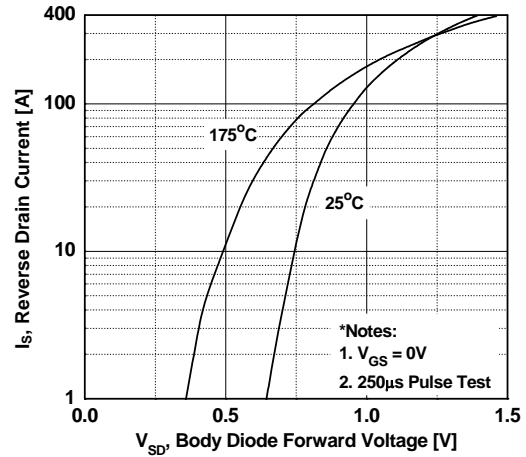


Figure 5. Capacitance Characteristics

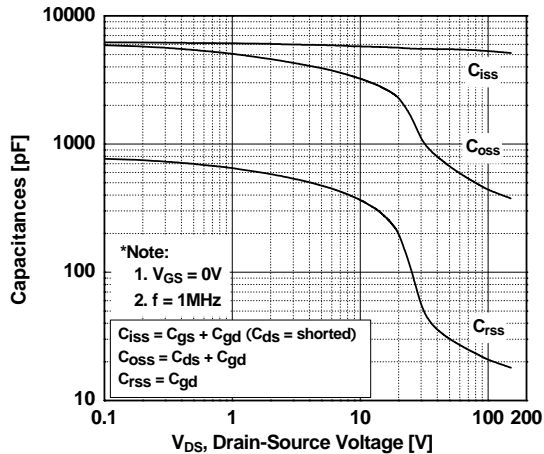
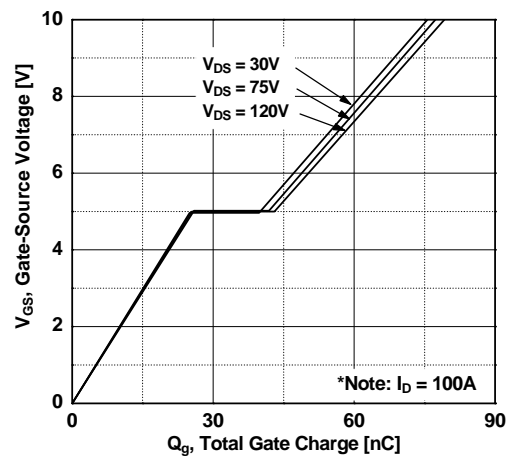


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

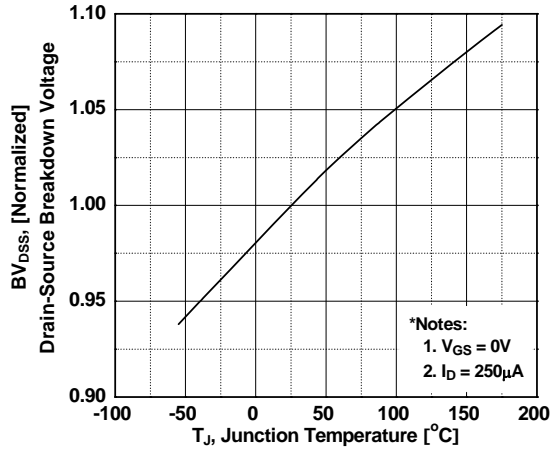


Figure 8. On-Resistance Variation vs. Temperature

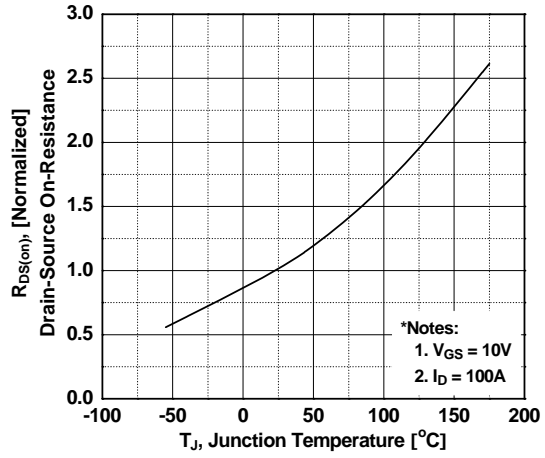


Figure 9. Maximum Safe Operating Area vs. Case Temperature

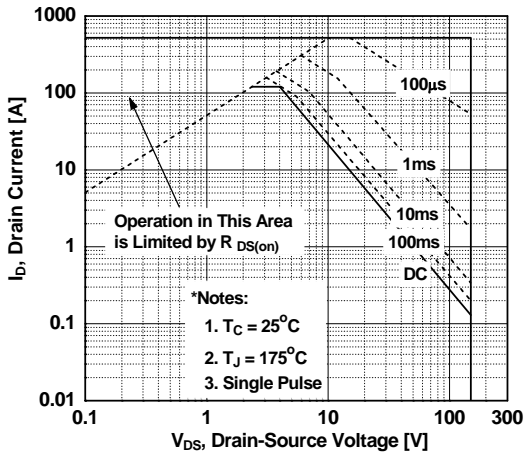


Figure 10. Maximum Drain Current

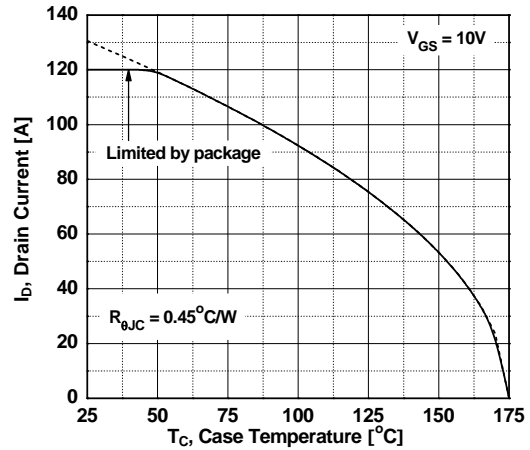


Figure 11. E_oss vs. Drain to Source Voltage

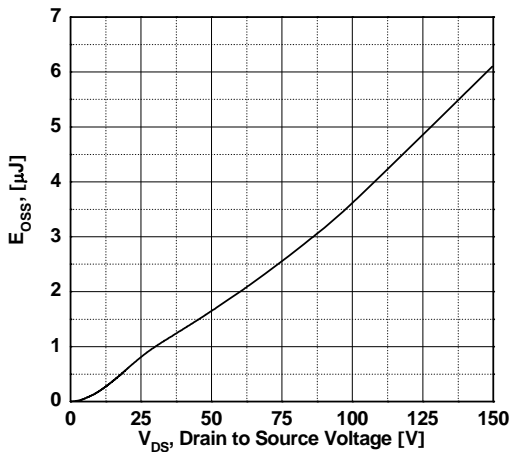
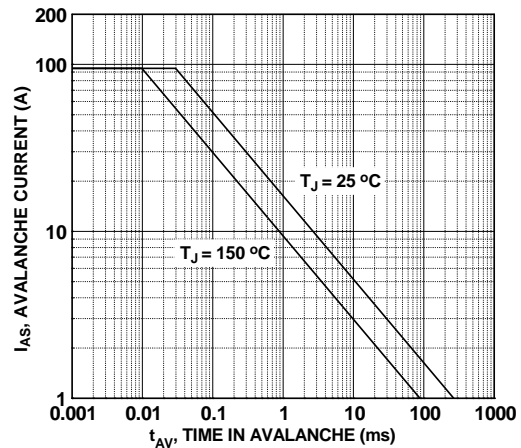
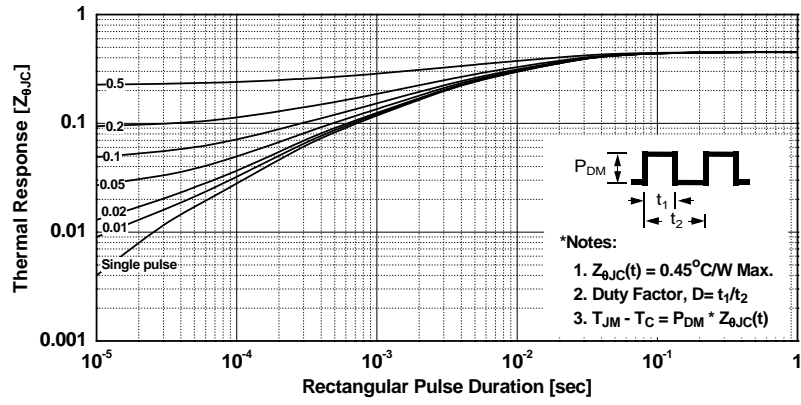


Figure 12. Unclamped Inductive Switching Capability

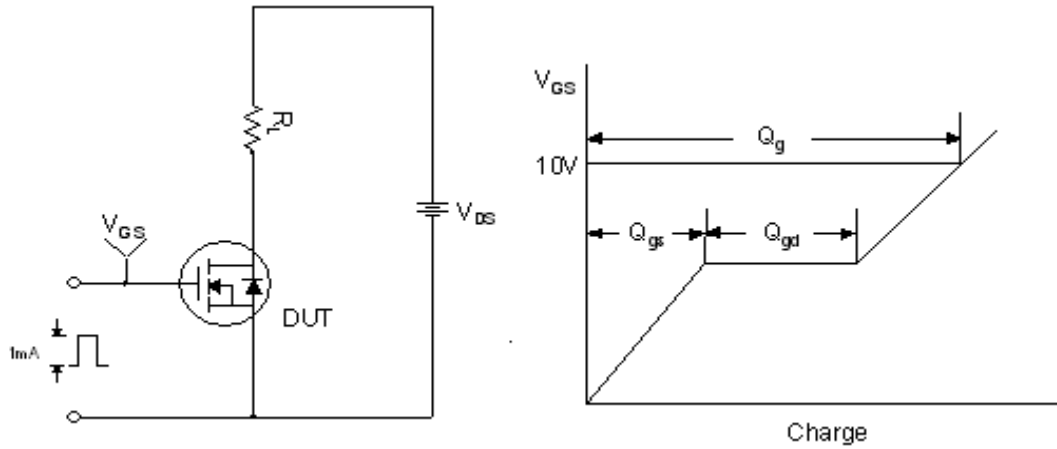


Typical Performance Characteristics (Continued)

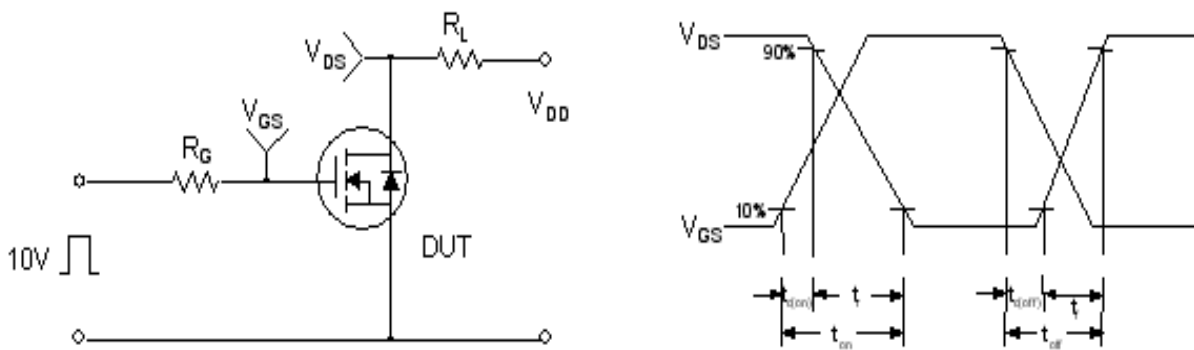
Figure 13. Transient Thermal Response Curve



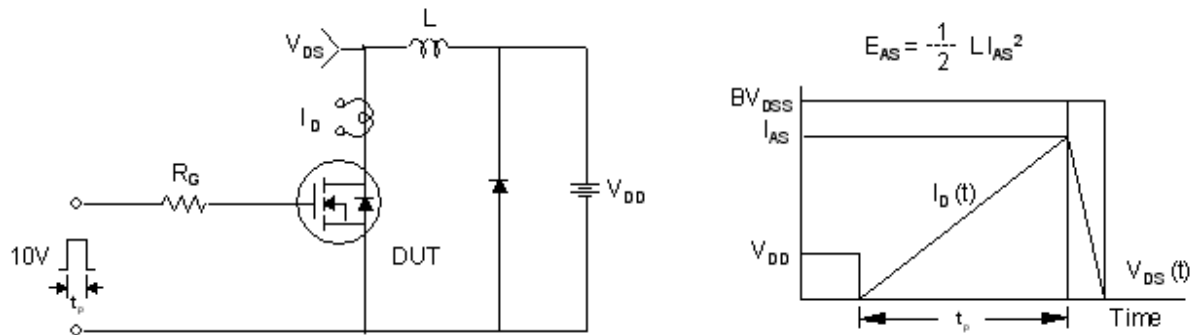
Gate Charge Test Circuit & Waveform



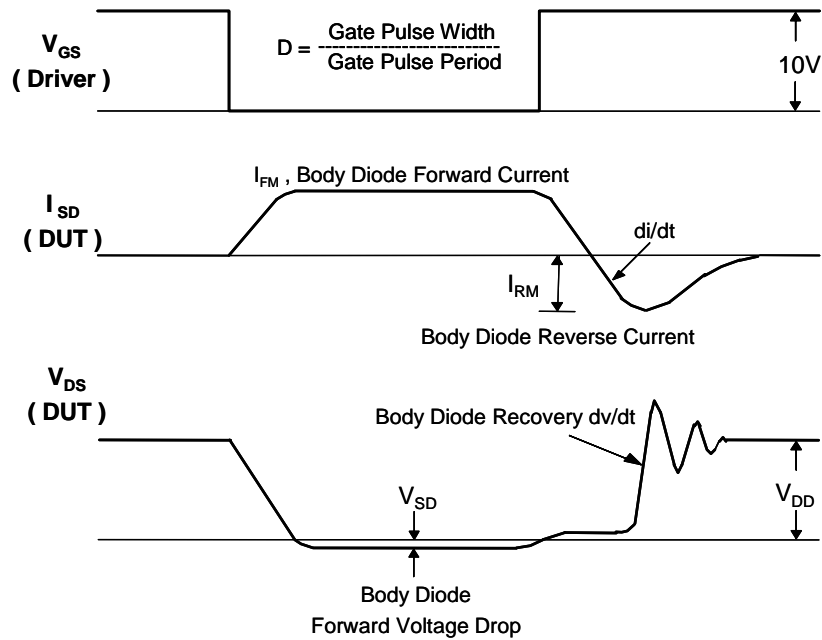
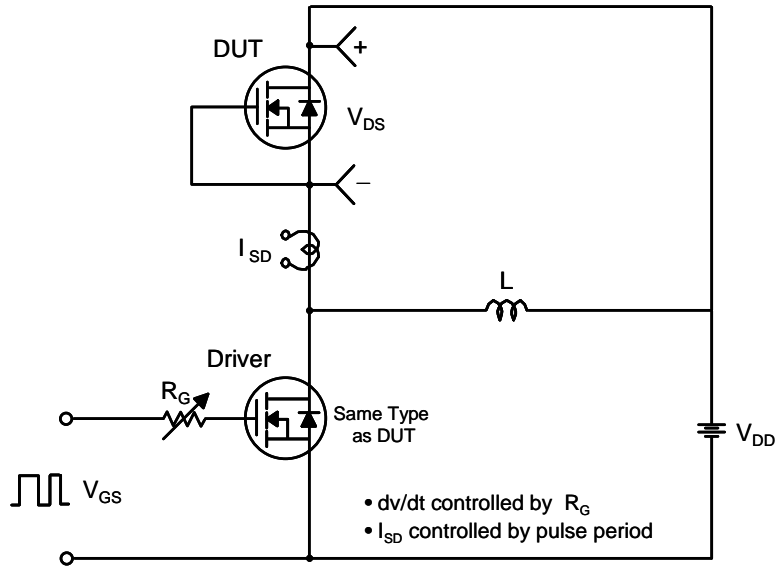
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

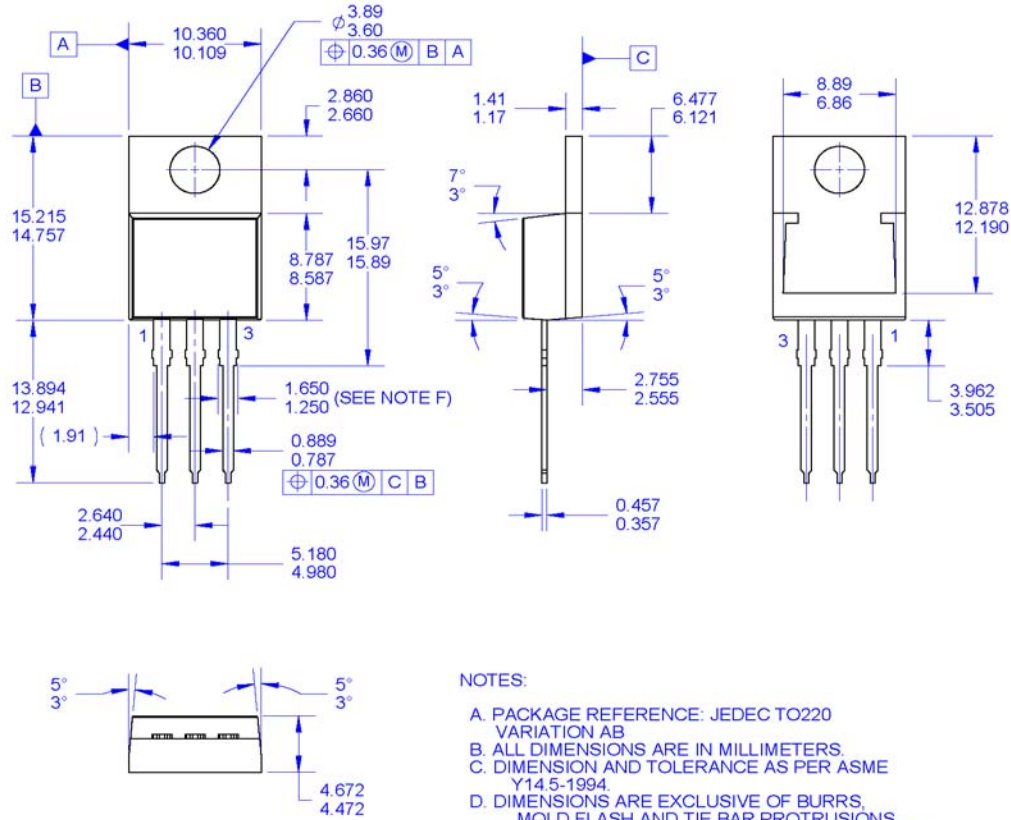


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Mechanical Dimensions

TO-220 (F102: Trimmed Leads)



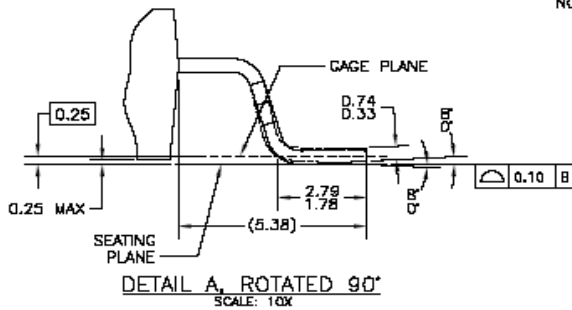
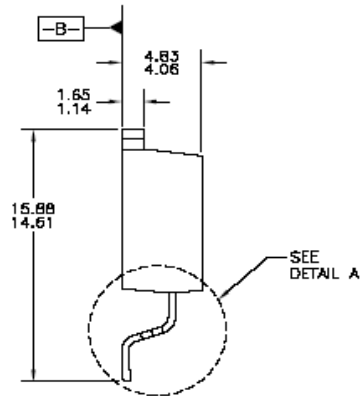
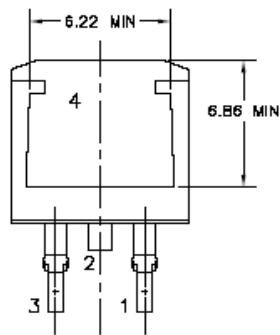
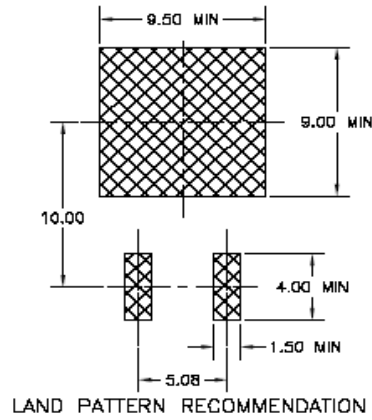
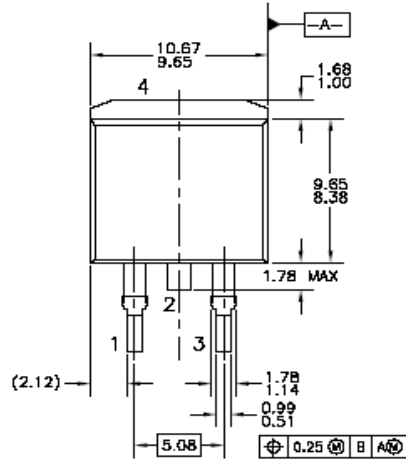
NOTES:

- A. PACKAGE REFERENCE: JEDEC TO220 VARIATION AB
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. THIS PACKAGE IS FSZZ INTERNAL PRODUCTION AND INTENDED FOR DELTA CUSTOMER ONLY.
- F. MAX WIDTH FOR F102 DEVICE = 1.35mm.
- G. DRAWING FILE NAME: TO220T03REV3

Dimensions in Millimeters

Mechanical Dimensions

D²PAK



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) ALL DIMENSIONS ARE IN MILLIMETERS.
 - B) REFERENCE JEDEC, TO-263, ISSUE D, VARIATION AB, DATED JULY 2003.
 - C) DIMENSIONING AND TOLERANCING PER ANSI Y14.5M - 1982.
 - D) LOCATION OF THE PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE).
 - E) PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL.

T02B3AD2REV D

Dimensions in Millimeters



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Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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